Features:
• Complete, Embedded 2.4 GHz IEEE 802.11 b/g Wireless LAN Module
• 14 General Purpose Input/Output (GPIO) Pins (Four GPIOs shared with UART)
• Eight Analog Sensor Inputs
• Small Surface-Mount Module: 1.050” x 0.700” x 0.125” (26.67 mm x 17.78 mm x 3.18 mm)
• Integrated Crystal, Internal Voltage Regulator, Matching Circuitry, Power Amplifier
• Integrates Easily into Final Product – Minimizes Product Development, Provides Quicker Time to Market
• Configured using Simple ASCII Commands

Networking:
- Supports Infrastructure and SoftAp Networking Modes
- Built-in Networking Applications: TCP, UDP, DHCP, DNS, ICMP, ARP, HTTP Client, and FTP Client
- Complete On-Board TCP/IP Networking Stack
- Unique MAC Address
- Upgrade Firmware Over the Air using FTP
- Supports Wi-Fi® Protected Setup (WPS)

Power Management:
• Ultra Low-Power Sleep Mode (4 uA)
• Perfect for Portable Battery Operated Devices
• Battery Boost Control Circuitry
• Real-Time Clock for Time Stamping, Auto-Sleep, and Auto-Wake

Antenna:
• External Antenna Connection via RF Pad
• Certified Antenna Types: Chip, Whip, PCB Trace, and Wire

Compliance:
• Modular Certified for the United States (FCC) and Canada (IC)
• European R&TTE Directive Assessed Radio Module
• Australia, New Zealand, Korea, Taiwan

Networks:
- Supports Infrastructure and SoftAp Networking Modes
- Built-in Networking Applications: TCP, UDP, DHCP, DNS, ICMP, ARP, HTTP Client, and FTP Client
- Complete On-Board TCP/IP Networking Stack
- Unique MAC Address
- Upgrade Firmware Over the Air using FTP
- Supports Wi-Fi® Protected Setup (WPS)

Power Management:
• Ultra Low-Power Sleep Mode (4 uA)
• Perfect for Portable Battery Operated Devices
• Battery Boost Control Circuitry
• Real-Time Clock for Time Stamping, Auto-Sleep, and Auto-Wake

Antenna:
• External Antenna Connection via RF Pad
• Certified Antenna Types: Chip, Whip, PCB Trace, and Wire

Compliance:
• Modular Certified for the United States (FCC) and Canada (IC)
• European R&TTE Directive Assessed Radio Module
• Australia, New Zealand, Korea, Taiwan
Table of Contents

1.0 Device Overview ............................................................................................................. 3
2.0 Circuit Description (Hardware Interface) .................................................................................... 9
3.0 Application Information..................................................................................................... 11
4.0 Regulatory Approval......................................................................................................... 15
5.0 Electrical Characteristics .................................................................................................. 21

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at docerrors@microchip.com or fax the Reader Response Form in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

• Microchip’s Worldwide Web site; http://www.microchip.com
• Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com to receive the most current information on all of our products.
1.0 DEVICE OVERVIEW

The RN171 is a standalone, embedded 802.11 b/g Wireless Local Area Network (WLAN) module. The module incorporates an on-board TCP/IP networking stack, cryptographic accelerator, power management subsystem, real-time clock, versatile sensor interface, 2.4 GHz transceiver, and RF power amplifier (see Figure 1-1). With the RN171, designers can embed Wi-Fi and networking functionality rapidly into virtually any device.

The RN171 provides cost and time-to-market savings as a self-contained internet-enabling solution. The module has been designed to provide designers with a simple Wi-Fi solution that features:

- Ease of integration and programming
- Vastly reduced development time
- Minimum system cost
- Long battery life
- Maximum value in a range of applications

The RN171 is configured with a simple ASCII command language. The “WiFly Command Reference, Advanced Features and Applications User’s Guide” (DS50002230) contains a complete listing and instructions of the ASCII command interface.

In the simplest configuration, the module requires only power, ground, and UART TX and RX connections. The RN171 module can interface to low-cost microcontrollers using only two wires, UART TX and RX.

The RN171 has a versatile sensor interface that can be used to monitor analog signals such as temperature, audio, motion, and acceleration.

The module has a small form factor, which makes it easy to integrate. Additionally, the module is compatible with standard pick-and-place equipment.

The RN171 is ideal for a vast range of applications that require long battery life, moderate processing power, moderate data throughput and occasional Wi-Fi connectivity, such as:

- Real-Time Locationing Systems (RTLS)
- Industrial and home automation
- Health and fitness monitoring
- Telemetry
- Security

Additionally, the module is perfect for mobile wireless applications such as asset monitoring and sensor applications.

The RN171 can independently maintain a low-power wireless network connection. Ultra-low power usage and flexible power management maximize the module’s lifetime in battery-operated devices. A wide operating temperature range allows use in indoor and outdoor environments (industrial temperature range).

When operating in Sleep mode, the module minimizes battery usage while still being able to respond to certain events, including internal timers and events on the sensor interfaces. Applications that make efficient use of the sleep state can extend battery life to multiple years.

The RN171 has modular device approval for operation in the United States (FCC) and Canada (IC). The RN171 module is an R&TTE Directive assessed radio module for operation in Europe.

FIGURE 1-1: RN171 BLOCK DIAGRAM
1.1 ASCII Command & Data Interface

The “WiFly Command Reference, Advanced Features and Applications User’s Guide” (DS50002230) provides a complete description of the ASCII command and data interface for the RN171 module.

1.2 Interface Description

Figure 1-1 shows the RN171 pin diagram. Figure 1-3 shows the microcontroller to RN171 interface. Table 1-1 describes the RN171 pins.

Note 1: Hardware flow control signals CTS and RTS should be used for baud rates of 115200 or greater.
**TABLE 1-1: PIN DESCRIPTION**

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Type</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>2</td>
<td>ISP_TX</td>
<td>DO</td>
<td>In-system programming transmit</td>
</tr>
<tr>
<td>3</td>
<td>ISP_RX</td>
<td>DI</td>
<td>In-system programming receive</td>
</tr>
<tr>
<td>4</td>
<td>GPIO9/SD_CLK/SCLK</td>
<td>DIO</td>
<td>General purpose I/O 9(2,3)/SDIO clock/SD-SPI slave SCLK</td>
</tr>
<tr>
<td>5</td>
<td>GPIO8/SD_D3/SS</td>
<td>DIO</td>
<td>General purpose I/O 8(2,4)/SDIO D3/SD-SPI slave select</td>
</tr>
<tr>
<td>6</td>
<td>GPIO7/SD_D2</td>
<td>DIO</td>
<td>General purpose I/O 7(2,4)/SDIO D2</td>
</tr>
<tr>
<td>7</td>
<td>GPIO6/SD_D1/INT</td>
<td>DIO</td>
<td>General purpose I/O 6(2,4)/SDIO D1/SD-SPI slave INT</td>
</tr>
<tr>
<td>8</td>
<td>GPIO5/SD_D0/MISO</td>
<td>DIO</td>
<td>General purpose I/O 5(2,4)/SDIO D0/SD-SPI slave MISO</td>
</tr>
<tr>
<td>9</td>
<td>GPIO4/SD_CMD/MOSI</td>
<td>DIO</td>
<td>General purpose I/O 4(2,4)/SDIO CMD/SD-SPI slave MOSI</td>
</tr>
<tr>
<td>10</td>
<td>VDD</td>
<td>Power</td>
<td>Positive supply</td>
</tr>
<tr>
<td>11</td>
<td>GPIO3</td>
<td>DIO</td>
<td>General purpose I/O 3(2,3)</td>
</tr>
<tr>
<td>12</td>
<td>GPIO2</td>
<td>DIO</td>
<td>General purpose I/O 2(2,3)</td>
</tr>
<tr>
<td>13</td>
<td>GPIO1</td>
<td>DIO</td>
<td>General purpose I/O 1(2,3)</td>
</tr>
<tr>
<td>14</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>15</td>
<td>SPI_CS</td>
<td>DO</td>
<td>SPI master chip select to internal Flash memory chip select. (Do not connect.)</td>
</tr>
<tr>
<td>16</td>
<td>SPI_MISO</td>
<td>DI</td>
<td>SPI master data Input to internal Flash memory data output. (Do not connect.)</td>
</tr>
<tr>
<td>17</td>
<td>SPI_SCK</td>
<td>DO</td>
<td>SPI master clock to internal Flash memory clock. (Do not connect.)</td>
</tr>
<tr>
<td>18</td>
<td>SPI_MOSI</td>
<td>DO</td>
<td>SPI master data output to internal Flash memory data input. (Do not connect.)</td>
</tr>
<tr>
<td>19</td>
<td>FLASH_POWER</td>
<td>Power</td>
<td>Internal Flash memory power. (Do not connect.)</td>
</tr>
<tr>
<td>20</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>21</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>22</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>23</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>24</td>
<td>ANT</td>
<td>AIO</td>
<td>RF antenna. 50Ω impedance</td>
</tr>
<tr>
<td>25</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>26</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>27</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>28</td>
<td>GND</td>
<td>Power</td>
<td>Ground reference</td>
</tr>
<tr>
<td>29</td>
<td>SENSOR0</td>
<td>AI</td>
<td>Sensor interface 0(5)</td>
</tr>
<tr>
<td>30</td>
<td>SENSOR1</td>
<td>AI</td>
<td>Sensor interface 1(5)</td>
</tr>
<tr>
<td>31</td>
<td>SENSOR2</td>
<td>AI</td>
<td>Sensor interface 2(5)</td>
</tr>
<tr>
<td>32</td>
<td>SENSOR3</td>
<td>AI</td>
<td>Sensor interface 3(5)</td>
</tr>
<tr>
<td>33</td>
<td>SENSOR_POWER</td>
<td>Power</td>
<td>Sensor power</td>
</tr>
<tr>
<td>34</td>
<td>VDD</td>
<td>Power</td>
<td>Positive supply</td>
</tr>
</tbody>
</table>

**Note 1:** Pin type abbreviation: A = Analog, D = Digital, I = Input, O = Output.

2: Refer to Electrical Specifications for GPIO voltage and current limitations.

3: Digital input/output (bidirectional) 8 mA drive, ~83 K internal pull-down. 3.3V tolerant. Reset State: Pull-down.

4: Digital input/output (bidirectional) 24 mA drive, no internal pull-down. 3.3V tolerant. Reset State: High-Z. Do not allow to float.

5: Analog input. 0-400 mV (Do not exceed 1.2V DC)
1.3 Mounting Details

Figure 1-4 and Figure 1-5 show the module’s physical dimensions. Figure 1-6 shows the recommended host PCB layout.

1.4 Soldering Recommendations

The RN171 wireless module was assembled using a standard lead-free reflow profile as shown in Figure 1-7. The module is compatible with standard lead-free solder reflow profiles. To avoid damaging the module, the following recommendations are given:

- Figure 1-8 gives a recommended reflow profile for this module
- Refer to the solder paste data sheet for specific reflow profile recommendations
- Use no-clean flux solder paste
- Do not wash as moisture can be trapped under the shield
- Use only one flow. If the PCB requires multiple flows, apply the module on the last flow
FIGURE 1-5:  RN171 MODULE PHYSICAL DIMENSIONS (BOTTOM VIEW)

Dimensions are in inches.
Tolerances:
- PCB Outline: +/- 0.005"
- PCB Thickness: +/- 0.001"

Note: Pads at:
- 0.190 x 0.890
- 0.260 x 0.025
- 0.575 x 1.035
are grounded plated through holes for shield mounting.

Recommend keeping host PCB top layer signal traces away (0.050" diameter).

FIGURE 1-6:  RECOMMENDED HOST PCB FOOTPRINT

FIGURE 1-7:  SOLDER REFLOW TEMPERATURE PROFILE

Note: Pad details:
- 0.190 x 0.890
- 0.260 x 0.025
- 0.575 x 1.035
are grounded plated through holes for shield mounting.
FIGURE 1-8: SOLDER REFLOW CURVE

Peak Temperature:
230°C (min)
240°C (max)

170°C

220°C (T1)

40°C

135 S (min)
180 S (max)

30 S (min)
65 S (max)

40 S (min)
60 S (max)

Note: Recommended Solder Paste to be used is OMNIX-310.
2.0 CIRCUIT DESCRIPTION
(HARDWARE INTERFACE)

The following sections describe the module's hardware interface.

2.1 UART Interface

The UART interface supports 2-wire (RX, TX) and 4-wire configurations with hardware flow control (RX, TX, CTS, and RTS). The logic levels are CMOS voltage levels (not RS-232 voltage levels). The UART interface supports baud rates of 2,400; 4,800; 9,600; 19,200; 38,400; 115,200; and 230,400 bits per second. Refer to the “WiFly Command Reference, Advanced Features and Applications User’s Guide” (DS50002230) for UART configuration information.

Note: Use hardware flow control for baud rates of 115,200 and higher.

2.2 SPI Master Interface

The RN171 module contains a master SPI interface (SPI_CS, SPI_CLK, SPI_MISO, and SPI_MOSI) that is connected to an internal Flash memory. Do not connect these pins on the host PCB.

2.3 SDIO Client Interface

The RN171 modules contain an SDIO client with SD-SPI mode and interface (SD_CLK/SCLK, SD_D3/SS, SD-D2, SD_D1/INT, SD_D0/MISO, and SD_CMD/MOSI). This interface is not currently implemented in the WiFly command reference.

2.4 In-System Programming (ISP)

The ISP_TX, ISP_RX, and other pins allow in-system programming of the module. The module’s firmware can be upgraded via ISP using a *.bin file.

Note: The over-the-air FTP update image file (*.img) is not compatible with the ISP.

Though it is optional, it is recommended to place the ISP header on the host PCB to facilitate firmware upgrades during development and manufacturing. The header is two row by 8-pin with 0.050 inch space and pitch (Samtech P/N FTSH-108-01-F-DV-K). Refer to Figure 3-3 for information about connecting to the module for ISP. The RN-ISP in-system programming interface connects to the module for ISP. Refer to the RN-ISP product page on the Microchip web site for more information.

2.5 Analog Sensor Interface

Sensors (0-3) can be used to wake the module. The sensor pins are 1.2V tolerant. When sensor pins are used as sensor inputs, they accept input voltages up to 1.2V but saturate at 400 mV.

WARNING

DO NOT apply voltages greater than 1.2V on any of the sensor pins.

The 14-bit ADC requires a 35 ms conversion time with 0.01% linearity.

Additionally, the module has a low-power interface for interfacing sensors such as push buttons, accelerometers, security seals, and motion sensors.

2.6 Sensor Interface

The sensor can interface to:
- Four switch sensors
- A motion sensor for use with external ball-in-tube
- A pulsed comparator
- A Sample Measurement Unit (SMU) ADC
- A current generator for measurement

The switch sensors, motion sensors, and pulsed comparator are available when the module is awake or asleep. The SMU ADC is only available when the module is awake. The sensor elements share the module’s eight sensor pins.

When the module is asleep, the sensor interface can be used to detect events such as a switch opening or closing, motion, or an analog voltage moving outside of a preset window. When the module is awake, the SMU can digitize the analog signals and make high-precision analog measurements.

2.7 General Purpose Input/Output (GPIO) Pins

The RN171 has 14 GPIO (GPIO1 through GPIO14) pins that can be commanded by ASCII commands. GPIO10 through GPIO14 pins have secondary functions for the UART (TX, RX, CTS, and RTS), while others can control connection modes, LEDs, etc.

Refer to the “WiFly Command Reference, Advanced Features and Applications User’s Guide” (DS50002230) for information on configuring and controlling the module.
2.8 Power Management

The module supports an ultra-low power sleep state, from which it can wake for a range of detected reasons. It transitions from asleep to CPU-active in 1.7 ms, and CPU active to network connection in less than 35 ms (typical). The RN171 also supports a keep-alive doze state that provides an instant transition to a wake state.

2.8.1 FORCE AWAKE

The RN171 may be forced awake by asserting the FORCE_AWAKE pin for at least 245 ms. If the FORCE_AWAKE pin remains asserted, the module is prevented from sleeping or dozing.

2.8.2 POWER SUPPLY

For supply voltages in the range of 3.0 to 3.7 volts, connect the module using the power supply (no boost circuit). Refer to Figure 3-1 for an example.

2.8.3 BATTERY BOOST CONTROL CIRCUIT

The RN171 includes a battery boost control circuitry for battery voltages in the range of 1.8 to 3.3V. Five external components as shown in Figure 3-2 make up the battery boost circuit.

2.9 Module Reset

There are several ways to Reset the module:

• A Power-On Reset is generated automatically when power is applied. This Reset is intended to initialize the module when a new battery is connected.
• Perform an external Power-On Reset by pulling the RESET pin low.
• Perform a soft Power-On Reset using software commands.
• A Reset can be triggered by a critical event, such as a brownout, generated if the supply voltage drops below the minimum operating voltage.

2.9.1 BROWN-OUT DETECTION

The RN171 includes a brown-out detector that holds the module in Reset if the battery voltage falls below the minimum operating voltage.

**WARNING**

The battery boost circuit should not be operated with battery supply voltages above 3.3 volts.

**Note:** If the RN171 module is used in battery applications, it is highly recommended that a voltage supervisory device be employed.
3.0 APPLICATION INFORMATION

The following sections provide application information, such as an application schematic and antenna information.

3.1 Schematic

Figure 3-1 and Figure 3-2 shows the RN171 application schematic for direct power and battery boost modes, respectively. Figure 3-3 shows a diagram with the optional ISP header.

FIGURE 3-1: RN171 APPLICATION SCHEMATIC – DIRECT POWER MODE
3.2 External Antenna Types

The RN171 module has a 50Ω antenna connection on pin 24. Connect to an antenna through a host PCB microstrip trace layout to an external connector, PCB trace antenna, or component (chip) antenna. This trace can be extended to include passive parts for antenna attenuation padding, impedance matching, or to provide test ports. Other components, such as amplifiers and active drivers, are not considered part of the trace layout and may void the RN171’s modular certification.

It is recommended that the trace layout from pin 24 to the external connector or antenna be as short as possible for minimum loss and best impedance matching. If the trace layout is longer, it should be a 50Ω impedance microstrip or coplanar waveguide PCB trace.

Adjacent ground pins 21-23 and 25-27 should be connected to a low-impedance ground plane on the host PCB.

Modular certification of the RN171 module was performed with the external antenna types listed in Table 3-1. An antenna type comprises antennas having similar in-band and out-of-band radiation patterns. Refer to Section 4.0 "Regulatory Approval" for specific regulatory requirements by country.
TABLE 3-1: TESTED EXTERNAL ANTENNA TYPES

<table>
<thead>
<tr>
<th>Type</th>
<th>Gain</th>
</tr>
</thead>
<tbody>
<tr>
<td>PCB Trace</td>
<td>0 dBi</td>
</tr>
<tr>
<td>Chip</td>
<td>1.07 dBi</td>
</tr>
<tr>
<td>Wire</td>
<td>0 dBi</td>
</tr>
<tr>
<td>Whip</td>
<td>2.2 dBi</td>
</tr>
</tbody>
</table>

Note 1: An antenna type comprises antennas having similar in-band and out-of-band radiation patterns.

3.2.1 PCB TRACE ANTENNA

Modular certification of the RN171 module was performed with the PCB trace antenna shown in Figure 3-4. The exact dimensions of the trace antenna must be followed. Gerber files for the PCB trace antenna are available on the RN171 product web page on the Microchip web site at http://www.microchip.com/rn171.

3.2.2 CHIP ANTENNA

Modular certification of the RN171 module was performed with the fractus (http://www.fractus.com) chip antenna part number FR05-S1-N-0-104. Peak gain listed in the data sheet is 1.07 dBi. Any chip antenna type may be used with the RN171 module provided the gain is equal to or less than 1.07 dBi, and having similar in-band and out-of-band radiation patterns as the fractus antenna. For proper operation of the chip antenna, refer to the data sheet for PCB footprint details and mounting considerations.

3.2.3 WIRE ANTENNA

Modular certification of the RN171 module was performed with the wire antenna shown in Figure 3-5. The antenna is an 18-gauge wire with a length of 1 inch ± 0.25. For best performance, the wire antenna should be perpendicular to a generous ground plane, preferably at least ¼ wavelength of 2.4 GHz (1.2 inches/30 mm).

3.2.4 WHIP ANTENNA

Modular certification of the RN171 module was performed with a whip antenna with a peak gain of 2.2 dBi. Any whip antenna type may be used with the RN171 module provided the gain is equal to or less than 2.2 dBi, and having similar in-band and out-of-band radiation patterns. Connection to the whip antenna can be by a U.FL. Figure 3-6 shows a suggested PCB layout for a U.FL connector.

FIGURE 3-4: PCB TRACE ANTENNA

Dimensions are in inches.

FIGURE 3-5: WIRE ANTENNA

The antenna is an 18-gauge wire with a length of 1 inch ± 0.25. For best performance, the wire antenna should be perpendicular to a generous ground plane, preferably at least ¼ wavelength of 2.4 GHz (1.2 inches/30 mm).

FIGURE 3-6: U.FL CONNECTOR

Dimensions are in inches.
4.0 REGULATORY APPROVAL

This section outlines the regulatory information for the RN171 module for the following countries:

• United States
• Canada
• Europe
• Australia
• New Zealand
• Korea
• Other Regulatory Jurisdictions

4.1 United States

The RN171 module has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C “Intentional Radiators” modular approval in accordance with Part 15.212 Modular Transmitter approval. Modular approval allows the end user to integrate the RN171 module into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation, provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user’s authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The finished product is required to comply with all applicable FCC equipment authorizations regulations, requirements and equipment functions not associated with the transmitter module portion. For example, compliance must be demonstrated to regulations for other transmitter components within the host product; to requirements for unintentional radiators (Part 15 Subpart B “Unintentional Radiators”), such as digital devices, computer peripherals, radio receivers, etc.; and to additional authorization requirements for the non-transmitter functions on the transmitter module (i.e., Verification, or Declaration of Conformity) (e.g., transmitter modules may also contain digital logic functions) as appropriate.

4.1.1 LABELING AND USER INFORMATION REQUIREMENTS

The RN171 module has been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording as follows:

Contains Transmitter Module FCC ID: T9J-RN171
or
Contains FCC ID: T9J-RN171

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

A user’s manual for the product should include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

• Reorient or relocate the receiving antenna.
• Increase the separation between the equipment and receiver.
• Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
• Consult the dealer or an experienced radio/TV technician for help.

Additional information on labeling and user information requirements for Part 15 devices can be found in KDB Publication 784748 available at the FCC Office of Engineering and Technology (OET) Laboratory Division Knowledge Database (KDB):

http://apps.fcc.gov/oetcf/kdb/index.cfm
4.1.2 RF EXPOSURE
All transmitters regulated by FCC must comply with RF exposure requirements. OET Bulletin 65, Evaluating Compliance with FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields, provides assistance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC). The bulletin offers guidelines and suggestions for evaluating compliance.

If appropriate, compliance with exposure guidelines for mobile and unlicensed devices can be accomplished by the use of warning labels and by providing users with information concerning minimum separation distances from transmitting structures and proper installation of antennas.

The following statement must be included as a CAUTION statement in manuals and OEM products to alert users of FCC RF exposure compliance:

To satisfy FCC RF Exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended.

The antenna(s) used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

If the RN171 module is used in a portable application (i.e., the antenna is less than 20 cm from persons during operation), the integrator is responsible for performing Specific Absorption Rate (SAR) testing in accordance with FCC rules 2.1091.

4.1.3 APPROVED EXTERNAL ANTENNA TYPES
To maintain modular approval in the United States, only the antenna types that have been tested shall be used. It is permissible to use different antenna manufacturers provided the same antenna type that has similar in-band and out-of-band radiation patterns and antenna gain (equal to or less than) is used.

Modular approval testing of the RN171 module was performed with the antenna types listed in Table 3-1.

4.1.4 HELPFUL WEB SITES
- Federal Communications Commission (FCC):
  http://www.fcc.gov
- FCC Office of Engineering and Technology (OET) Laboratory Division Knowledge Database (KDB):
  http://apps.fcc.gov/oetcf/kdb/index.cfm

4.2 Canada
The RN171 module has been certified for use in Canada under Industry Canada (IC) Radio Standards Specification (RSS) RSS-210 and RSSGen. Modular approval permits the installation of a module in a host device without the need to recertify the device.

4.2.1 LABELING AND USER INFORMATION REQUIREMENTS
Labeling Requirements for the Host Device (from Section 3.2.1, RSS-Gen, Issue 3, December 2010): The host device shall be properly labeled to identify the module within the host device.

The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labeled to display the Industry Canada certification number of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 6514A-RN171

User Manual Notice for License-Exempt Radio Apparatus (from Section 7.1.3 RSS-Gen, Issue 3, December 2010): User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L’exploitation est autorisée aux deux conditions suivantes: (1) l’appareil ne doit pas produire de brouillage, et (2) l’utilisateur de l’appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d’en compromettre le fonctionnement.
Transmitter Antenna (from Section 7.1.2 RSS-Gen, Issue 3, December 2010): User manuals for transmitters shall display the following notice in a conspicuous location:

The above notice may be affixed to the device instead of displayed in the user manual.

User manuals for transmitters equipped with detachable antennas shall also contain the following notice in a conspicuous location:

Immediately following the above notice, the manufacturer shall provide a list of all antenna types approved for use with the transmitter, indicating the maximum permissible antenna gain (in dBi) and required impedance for each.

4.2.2 APPROVED EXTERNAL ANTENNA TYPES

Transmitter Antenna (from Section 7.1.2 RSS-Gen, Issue 3, December 2010):

The RN171 module can only be sold or operated with antennas with which it was approved. Transmitter may be approved with multiple antenna types. An antenna type comprises antennas having similar in-band and out-of-band radiation patterns. Testing shall be performed using the highest gain antenna of each combination of transmitter and antenna type for which approval is being sought, with the transmitter output power set at the maximum level. Any antenna of the same type having equal or lesser gain as an antenna that had been successfully tested with the transmitter, will also be considered approved with the transmitter, and may be used and marketed with the transmitter.

When a measurement at the antenna connector is used to determine RF output power, the effective gain of the device's antenna shall be stated, based on measurement or on data from the antenna manufacturer. For transmitters of output power greater than 10 milliwatts, the total antenna gain shall be added to the measured RF output power to demonstrate compliance to the specified radiated power limits.

Modular approval testing of the RN171 module was performed with the antenna types listed in Table 3-1.

4.2.3 HELPFUL WEB SITES

Industry Canada: http://www.ic.gc.ca

4.3 Europe

The RN171 module is an R&TTE Directive assessed radio module that is CE marked and has been manufactured and tested with the intention of being integrated into a final product.

The RN171 module has been tested to R&TTE Directive 1999/5/EC Essential Requirements for Health and Safety (Article (3.1(a)), Electromagnetic Compatibility (EMC) (Article 3.1(b)), and Radio (Article 3.2) and are summarized in Table 4-1. A Notified Body Opinion has also been issued. All test reports are available on the RN171 product web page at http://www.microchip.com.

**Note:** To maintain conformance to the testing listed in Table 4-1, the module shall be installed in accordance with the installation instructions in this data sheet and shall not be modified.

When integrating a radio module into a completed product the integrator becomes the manufacturer of the final product and is therefore responsible for demonstrating compliance of the final product with the essential requirements of the R&TTE Directive.

### 4.3.1 LABELING AND USER INFORMATION REQUIREMENTS

The label on the final product which contains the RN171 module must follow CE marking requirements. The R&TTE Compliance Association Technical Guidance Note 01 provides guidance on final product CE marking.

### 4.3.2 EXTERNAL ANTENNA REQUIREMENTS

From R&TTE Compliance Association document Technical Guidance Note 01:

Provided the integrator installing an assessed radio module with an integral or specific antenna and installed in conformance with the radio module manufacturer’s installation instructions requires no further evaluation under Article 3.2 of the R&TTE Directive and does not require further involvement of an R&TTE Directive Notified Body for the final product. [Section 2.2.4]

The European Compliance Testing listed in Table 4-1 was performed using the antenna types listed in Table 3-1.

### 4.3.3 HELPFUL WEB SITES

A document that can be used as a starting point in understanding the use of Short Range Devices (SRD) in Europe is the European Radio Communications Committee (ERC) Recommendation 70-03 E, which can be downloaded from the European Radio Communications Office (ERO) at: http://www.ero.dk/.

Additional helpful web sites are:

- European Radio Communications Office (ERO): http://www.ero.dk
- The Radio and Telecommunications Terminal Equipment Compliance Association (R&TTE CA): http://www.rtteca.com/

### TABLE 4-1: EUROPEAN COMPLIANCE TESTING

<table>
<thead>
<tr>
<th>Certification</th>
<th>Standard</th>
<th>Article</th>
<th>Laboratory</th>
<th>Report Number</th>
<th>Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Health</td>
<td>EN 50371:2002-03</td>
<td></td>
<td></td>
<td>W6M21012-11105-50371</td>
<td>2011-04-08</td>
</tr>
<tr>
<td>EMC</td>
<td>EN 301 489-1 V1.8.1 (2008-04)</td>
<td>(3.1(b))</td>
<td></td>
<td>W6M21012-11105-E-16</td>
<td>2011-02-08</td>
</tr>
<tr>
<td>Radio</td>
<td>EN 301 489-17 V2.1.1 (2009-05)</td>
<td>(3.2)</td>
<td></td>
<td>W6M21012-11105-50371</td>
<td>2011-04-07</td>
</tr>
</tbody>
</table>
4.4 Australia

The Australia radio regulations do not provide a modular approval policy similar to the United States (FCC) and Canada (IC). However, RN171 module RF transmitter test reports can be used in part to demonstrate compliance in accordance with ACMA Radio communications “Short Range Devices” Standard 2004 (The Short Range Devices standard calls up the AS/NZS 4268:2008 industry standard). The RN171 module test reports can be used as part of the product certification and compliance folder. For more information on the RF transmitter test reports, contact Microchip Technology Australia sales office.

To meet overall Australian final product compliance, the developer must construct a compliance folder containing all relevant compliance test reports e.g. RF, EMC, electrical safety and DoC (Declaration of Conformity) etc. It is the responsibility of the developer to know what is required in the compliance folder for ACMA compliance. All test reports are available on the RN171 product web page at http://www.microchip.com. For more information on Australia compliance, refer to the Australian Communications and Media Authority web site http://www.acma.gov.au/.

4.4.1 EXTERNAL ANTENNA REQUIREMENTS

The compliance testing listed in Table 4-1 was performed using the antenna types listed in Table 3-1.

4.4.2 HELPFUL WEB SITES

The Australian Communications and Media Authority: www.acma.gov.au/.

4.5 New Zealand

The New Zealand radio regulations do not provide a modular approval policy similar to the United States (FCC) and Canada (IC). However, RN171 module RF transmitter test reports can be used in part to demonstrate compliance against the New Zealand “General User Radio License for Short Range Devices”. New Zealand Radio communications (Radio Standards) Notice 2010 calls up the AS / NZS 4268:2008 industry standard. The RN171 module test reports can be used as part of the product certification and compliance folder. All test reports are available on the RN171 product web page at http://www.microchip.com. For more information on the RF transmitter test reports, contact Microchip Technology sales office.

Information on the New Zealand short range devices license can be found in the following web links:


To meet overall New Zealand final product compliance, the developer must construct a compliance folder containing all relevant compliance test reports e.g. RF, EMC, electrical safety and DoC (Declaration of Conformity) etc. It is the responsibility of the developer to know what is required in the compliance folder for New Zealand Radio communications. For more information on New Zealand compliance, refer to the web site http://www.rsm.govt.nz/.

4.5.1 EXTERNAL ANTENNA REQUIREMENTS

The compliance testing listed in Table 4-1 was performed using the antenna types listed in Table 3-1.

4.5.2 HELPFUL WEB SITES


4.6 Korea

The RN171 module has received certification of conformity in accordance with the Radio Waves Act. Integration of this module into a final product does not require additional radio certification provided installation instructions are followed and no modifications of the module are allowed.

4.6.1 LABELING AND USER INFORMATION REQUIREMENTS

The label on the final product which contains the RN171 module must follow KC marking requirements. The integrator of the module should refer to the labeling requirements for Korea available on the Korea Communications Commission (KCC) website.

The RN171 module is labeled with its own KC mark. The final product requires the KC mark and certificate number of the module:

KCC-CRI-029-RN-171

4.6.2 EXTERNAL ANTENNA REQUIREMENTS

The Korea compliance testing was performed using the antenna types listed in Table 3-1.

4.6.3 HELPFUL WEB SITES

- Korea Communications Commission (KCC): http://www.kcc.go.kr
4.7 Taiwan

The RN171 module has received compliance approval in accordance with the Telecommunications Act. Customers seeking to use the compliance approval in their product should contact Microchip Technology sales or distribution partners to obtain a Letter of Authority.

Integration of this module into a final product does not require additional radio certification provided installation instructions are followed and no modifications of the module are allowed.

4.8 Other Regulatory Jurisdictions

Should other regulatory jurisdiction certification be required by the customer, or the customer need to recertify the module for other reasons, a certification utility is available. For further regulatory certification utility and documentation, contact your local Microchip Technology sales office.
## 5.0 ELECTRICAL CHARACTERISTICS

### TABLE 5-1: ENVIRONMENTAL CONDITIONS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature Range (Operating)</td>
<td>-40°C–85°C</td>
</tr>
<tr>
<td>Temperature Range (Storage)</td>
<td>-40°C–85°C</td>
</tr>
<tr>
<td>Relative Humidity (Operating)</td>
<td>≤ 90%</td>
</tr>
<tr>
<td>Relative Humidity (Storage)</td>
<td>≤ 90%</td>
</tr>
<tr>
<td>Moisture Sensitivity Level</td>
<td>1</td>
</tr>
</tbody>
</table>

### TABLE 5-2: ELECTRICAL CHARACTERISTICS (PROVISIONAL)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage (VBATT Option)</td>
<td>3.0</td>
<td>3.3</td>
<td>3.7</td>
<td>VDC</td>
</tr>
<tr>
<td>Digital Input</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Logic High VIH</td>
<td>2.3</td>
<td></td>
<td></td>
<td>VDC</td>
</tr>
<tr>
<td>Input Logic Low VIL</td>
<td></td>
<td>1.0</td>
<td></td>
<td>VDC</td>
</tr>
<tr>
<td>Digital Output Drive</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>GPIO 4, 5, 6, 7, 8</td>
<td>24</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>GPIO 9, 10, 11, 12, 13</td>
<td>8</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Power Consumption</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Sleep</td>
<td>4</td>
<td></td>
<td></td>
<td>μA</td>
</tr>
<tr>
<td>Standby (Doze)</td>
<td>15</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Connected (Idle, RX)</td>
<td>40</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Connected (TX) 0 dBm</td>
<td>120</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Connected (TX) 12 dBm</td>
<td>190</td>
<td></td>
<td></td>
<td>mA</td>
</tr>
</tbody>
</table>

### TABLE 5-3: MODULE DIMENSIONS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Dimensions</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Size</td>
<td>26.67 x 17.78 x 3.18</td>
<td>mm</td>
</tr>
</tbody>
</table>

### TABLE 5-4: ANALOG SENSOR INPUTS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sensor 0, 1, 2, 3 Wakeup Detection Threshold</td>
<td>500 mV</td>
</tr>
<tr>
<td>AD Sensor 0-7 Measurement Range</td>
<td>0-400 mV (Do not exceed 1.2V DC)</td>
</tr>
<tr>
<td>Resolution</td>
<td>14 bits = 12 μV</td>
</tr>
<tr>
<td>Accuracy</td>
<td>5% Uncalibrated, 0.01% Calibrated</td>
</tr>
<tr>
<td>Minimum Conversion Time</td>
<td>35 μs (5 kHz over Wi-Fi)</td>
</tr>
<tr>
<td>Sensor Power (Pin 33) Output Resistance 3.3V</td>
<td>10 Ω, Maximum Current = 50 mA</td>
</tr>
</tbody>
</table>
### TABLE 5-5: RADIO CHARACTERISTICS

<table>
<thead>
<tr>
<th>Parameters</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Frequency</td>
<td>2.412 to 2.462 GHz</td>
</tr>
<tr>
<td>Modulation</td>
<td>802.11b Compatibility: DSSS (CCK-11, CCK-5.5, DQPSK-2, DBPSK-1) 802.11g: OFDM</td>
</tr>
<tr>
<td>Channel Intervals</td>
<td>5 MHz</td>
</tr>
<tr>
<td>Channels</td>
<td>1-11</td>
</tr>
<tr>
<td>Transmission Rate (Over the Air)</td>
<td>1-11 Mbps for 802.11b/6-54 Mbps for 802.11g</td>
</tr>
<tr>
<td>Receive Sensitivity</td>
<td>-83 dBm Typical</td>
</tr>
<tr>
<td>Output Level (Class1)</td>
<td>-2 dBm to +12 dBm (Configurable via Software)</td>
</tr>
</tbody>
</table>

### TABLE 5-6: TRANSMITTER AC CHARACTERISTICS

<table>
<thead>
<tr>
<th>Output Power</th>
<th>802.11 b (2 Mbps) Current in mA(1)</th>
<th>802.11 g (24 Mbps) Current in mA(1)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0</td>
<td>120</td>
<td>135</td>
</tr>
<tr>
<td>2</td>
<td>130</td>
<td>150</td>
</tr>
<tr>
<td>4</td>
<td>170</td>
<td>190</td>
</tr>
<tr>
<td>6</td>
<td>175</td>
<td>200</td>
</tr>
<tr>
<td>8</td>
<td>180</td>
<td>210</td>
</tr>
<tr>
<td>10</td>
<td>185</td>
<td>225</td>
</tr>
<tr>
<td>12</td>
<td>190</td>
<td>240</td>
</tr>
</tbody>
</table>

**Note 1:** Measured at 3.3V DC VCC. The power consumption is the average power, active during actual power consumption.

### TABLE 5-7: BOOST (3.3V) REGULATOR CHARACTERISTICS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Units</th>
<th>Test Conditions/Comments</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Voltage</td>
<td>1.8</td>
<td>—</td>
<td>3.3</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Output Voltage (VDD_3V3)</td>
<td>—</td>
<td>3.3</td>
<td>—</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Maximum Output Current</td>
<td>—</td>
<td>—</td>
<td>350</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Conversion Efficiency</td>
<td>—</td>
<td>80</td>
<td>—</td>
<td>%</td>
<td></td>
</tr>
<tr>
<td>Switching Frequency</td>
<td>—</td>
<td>500</td>
<td>—</td>
<td>kHz</td>
<td></td>
</tr>
<tr>
<td>Load Capacitance</td>
<td>—</td>
<td>20</td>
<td>—</td>
<td>µF</td>
<td>Ceramic X5R or X7R</td>
</tr>
<tr>
<td>Switch Element Drive Current</td>
<td>—</td>
<td>100</td>
<td>—</td>
<td>mA</td>
<td></td>
</tr>
</tbody>
</table>
APPENDIX A:  REVISION HISTORY

Revision A (February 2014)

This is the initial released version of the document in the Microchip format. This replaces Roving Networks RN171 Data Sheet.
THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user’s guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip’s customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under “Support”, click on “Customer Change Notification” and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support
## PRODUCT IDENTIFICATION SYSTEM

To order parts, including industrial, or obtain information, for e.g., on pricing or delivery, refer to the factory or the listed sales office.

<table>
<thead>
<tr>
<th>PART NO.</th>
<th>I</th>
<th>RM</th>
<th>XXX</th>
<th>Examples:</th>
</tr>
</thead>
<tbody>
<tr>
<td>Device</td>
<td>Temp Range</td>
<td>Radio Module</td>
<td>Firmware Revision Number</td>
<td>a) RN171-I/RM = Industrial Temp</td>
</tr>
</tbody>
</table>

- **Device**: RN171; Vcc range 3.0V to 3.7V
- **Temperature Range**: I = -40°C to +85°C (Industrial Temperature)
Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip’s Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip’s code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer’s risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks
The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELoo, KEELoo logo, MPLAB, PIC, PICmicro, PICSTART, PIC32 logo, rPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.
FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.
Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.
Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rFLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-.Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.
SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.
GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. & KG, a subsidiary of Microchip Technology Inc., in other countries.
All other trademarks mentioned herein are property of their respective companies.
© 2014, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.
Printed on recycled paper.
ISBN: 9781620779491

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV
ISO/TS 16949

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company’s quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip’s quality system for the design and manufacture of development systems is ISO 9001:2000 certified.